

TECHNICAL DATA SHEET

Date
 11/20/2013

Product Name:	NFC
Product Description:	<p>NFC is a fluoride-free, general-purpose system for soldering gold, silver and copper based alloys, as well as most steels. Works well with all gold and silver solders. Paste is nondrying and has exceptional shelf-life in excess of one year. Paste is sensitive to storage temperature variations which can be good, or bad. Storage at temperatures in excess of 90°F for prolonged periods can cause the paste to separate. This can be fixed by mixing the paste with no adverse affect on its performance. For best results, store at temperatures below 80°F. Storage of paste in a refrigerator is not needed, although doing so will not hurt the paste.</p> <p>This product works best with slightly aggressive heating techniques with more focus of the torch on the paste deposit after the binder has burned off. It is also suitable for use with resistance and induction soldering techniques, and has limited use in furnace soldering.</p> <p>The paste deposit is fluid and will spread when heated before the flux begins to melt. The flux in this product is not very fluid and will tend to stay localized once it begins to melt.</p> <p>Flux residues are slightly more tenacious than our standard paste fluxes, but can still be removed with a water quench after soldering, by cleaning with warm soapy water once cool, via ultrasonic, or by agitation.</p>
Metal Percentage:	Typical metal content is 55-70% metal powder by weight.
Working Range:	1000-1600°F
Suitable Filler Metals:	This product has been tested with most silver brazing alloys, gold solder alloys and copper-phosphorous brazing alloys with good results.
Reference Documents:	Material Safety Data Sheet: MSDS-NFC.pdf Using Paste Solder: usingpaste.pdf